Onur Beker

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EDUCATION

Bogazici University   *2014 - Present*
Electrical and Electronics Engineering, Junior
GPA: 3.93/4.00

Tsukuba University   *2017 - 2018*
Exchange Student

Izmir Science High School   *2010 - 2014*
High School

RESEARCH EXPERIENCE

Max Planck Institute for Intelligent Systems   June 2018 – September 2018
Research Intern at Physical Intelligence Department   *Stuttgart, Germany*

- Designed a new method for the self-assembly and actuation of microrobots, using dielectrophoresis. Details of our work can be found in the corresponding article in Nature Materials.

Harvard-MIT Health Sciences & Technology/MGH,   June 2019 – September 2019
Athinoula A. Martinos Center for Biomedical Imaging   *Boston, U.S*
Research Intern at MR Physics and Instrumentation Group

- Built an MRI artifact reduction method that uses only scan-specific data. My work there is summarized in the corresponding ISMRM abstracts.

PUBLICATIONS

- Yunus Alapan, Berk Yigit, **Onur Beker**, Ahmet F. Demirörs, Metin Sitti. "Shape-encoded programmable dynamic assembly of mobile micromachines". *Nature Materials, 2019.* [link]

- **Onur Beker**, Congyu Liao, Jaejin Cho, Zijing Zhang, Kawin Setsompop, and Berkin Bilgic. "Scan-specific, Parameter-free Artifact Reduction in K-space (SPARK)". *(submitted to) ISMRM, 2020.* [link]

- Jaejin Cho, Congyu Liao, Zijing Zhang, Wei-Ching Lo, Jinmin Xu, **Onur Beker**, Kawin Setsompop, and Berkin Bilgic. "Highly Accelerated EPI with Wave Encoding and Multi-shot Simultaneous MultiSlice Imaging". *(submitted to) ISMRM, 2020.* [link]

SCHOLARSHIPS AND AWARDS

JASSO Scholarship for Short Term Study in Japan (2017 – 2018)
Awarded by the Japanese Ministry of Education, Culture, Sports, Science and Technology.

BUMED Extensive Success Scholarship (2014 – 2019)
Awarded by Bogazici University Alumni Association

Merit Based Prime Ministry Scholarship for Higher Education (2014 – 2019)
Awarded by Turkish Government for 65th degree in Undergraduate Placement Examination (LYS)

SKILLS

- **Programming:** Python, MATLAB, C/C++, Java, VHDL
- **Python:** NumPy, SciPy, Pytorch, Tensorflow, Keras
- **Tools:** Solidworks, COMSOL, PSpice, XILINX
- **Lab Work:** Microscopy, Nanoscribe, Image-J
- **Other:** Linux, Shell Scripts, Microsoft Office and other common applications for Windows

LANGUAGES

- **English**: Professional, (TOEFL IBT score: 112/120, GRE Verbal Score: 163/170)
- **Turkish**: Native Speaker
- **Japanese**: Conversational